

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JYUNKO ISOMURA	04/03/2018
SHINTARO IIDA	04/03/2018
HIDEAKI SAKURAI	04/03/2018
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16064383
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<b>ATTORNEY DOCKET NUMBER:</b>	06920/006902-US0
<b>NAME OF SUBMITTER:</b>	KAZUE TURIANO FOR MH
<b>SIGNATURE:</b>	/kazue turiano/
<b>DATE SIGNED:</b>	06/20/2018
<b>Total Attachments: 3</b>	
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COMBINED DECLARATION AND ASSIGNMENT

We, (1) Jyunko ISOMURA; (2) Shintaro IIDA; and (3) Hideaki SAKURAI, having a residence at (1) to (3) c/o MITSUBISHI MATERIALS CORPORATION, Central Research Institute, 1002-14, Mukohyama, Naka-shi, Ibaraki 311-0102 Japan (hereinafter "ASSIGNOR") declare that we believe we are the original inventors or original joint inventors of the subject matter which is described and claimed and for which a patent is sought on the invention entitled:

WATER-BASED ELECTRODEPOSITION DISPERSION FOR FORMING INSULATING FILM

which is described and illustrated;

in the attached application indicated with the docket number listed above, or

in the United States application or PCT Application Number PCT/JP2016/078424 filed on September 27, 2016

In consideration of the sum of Ten Dollars (\$10.00), or the equivalent thereof, and other good and valuable consideration, the sufficiency of which and receipt of which are hereby acknowledged, paid to ASSIGNOR by

MITSUBISHI MATERIALS CORPORATION

a Corporation having a place of business at 3-2, Otomachi 1-chome, Chiyoda-ku, Tokyo 100-8117 Japan (hereinafter "ASSIGNEE"), we do hereby sell and assign to said ASSIGNEE, its successors and assigns, the entire right, title, and interest, throughout the world in and to our Invention and Application; and all patents, divisions, reissues, continuations, continuation-in-parts and any extensions thereof and rights of priority therein, said interest being our entire ownership interest in the same, to be held and enjoyed by said ASSIGNEE, its successors, assigns, or other legal representatives, to the full end of the term thereof, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made, including all rights of Assignor to recover for past infringement thereof;

We hereby state that the Application was made or was authorized to be made by us. We have reviewed and understand the contents of the above identified specification, claims and

drawings, as amended by an amendment, if any, specifically referred to herein. We acknowledge that we are aware of the duty to disclose all information known to us that is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

And for the consideration aforesaid, we hereby covenant and agree to and with said ASSIGNEE, its successors and assigns, that whenever ASSIGNEE, its counsel or representative, or the counsel or representative of its successors or assigns, shall advise that an amendment to, or a division of, or any other proceeding or action in connection with an application concerning said Invention, including interference proceedings, is lawful and desirable, or that a reissue or continuation or extension of such application or patent issuing therefrom is lawful and desirable, we will sign all papers and drawings, take all rightful oaths and affidavits, and do all acts necessary or required to be done for the procurement of all lawful rights associated with the Invention, or for the reissue or continuation or extension of the same, will do all acts necessary or required to secure in said ASSIGNEE, its successors or assigns, the title to and full benefit of all rights hereby assigned, without charge to said ASSIGNEE or its successors or assigns, but at its or their expense; and we hereby appoint every present or future officer of said ASSIGNEE as our agent to sign all such papers and to do all such necessary acts on our behalf, to the fullest extent permitted by law;

And we hereby authorize and request the Commission of Patents and Trademarks and any other granting authority to issue any Letters Patent resulting from said Invention and application(s) concerning same to said ASSIGNEE.

This assignment shall have an effective date corresponding to the last date of execution.

We declare under penalty of perjury under the laws of the United States of America, and under penalty of the laws of any other jurisdiction before which this document may be presented, that we have signed this document as my own free act and that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that any willful false statements made in this declaration are punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Dated: 3 / Apr. / 2018  
(Day/Month/Year)

Jyunko Isomura  
Jyunko ISOMURA, Inventor

Leason Ellis Docket No.:

Dated: 3/Apr./2018  
(Day/Month/Year)

Shintaro Iida  
Shintaro IIDA, Inventor

Dated: 3/Apr./2018  
(Day/Month/Year)

Hideaki Sakurai  
Hideaki SAKURAI, Inventor